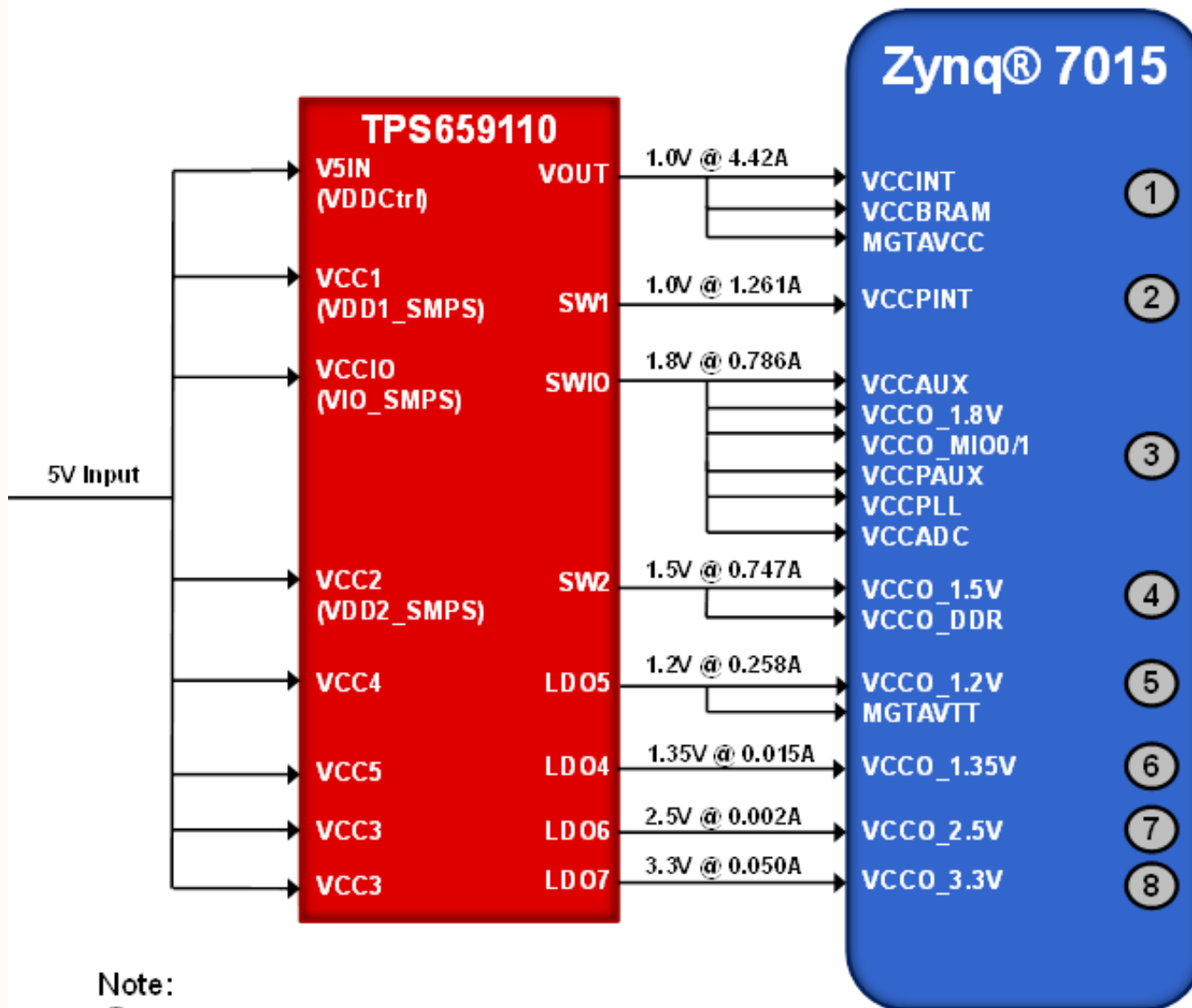


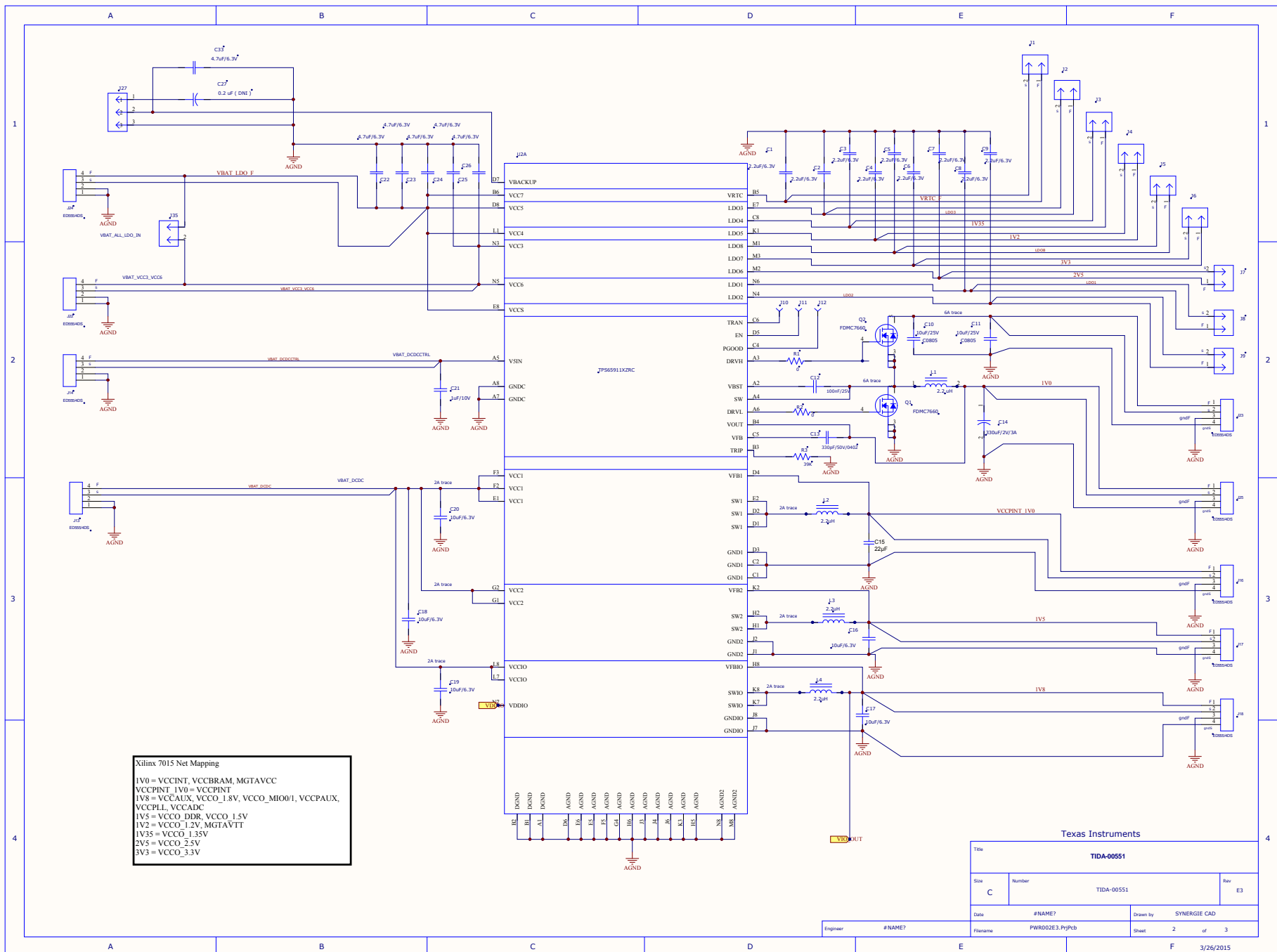
TPS659110 Zynq 7015 8 Watt Block Diagram



Note:

(X) = Power Sequence Order

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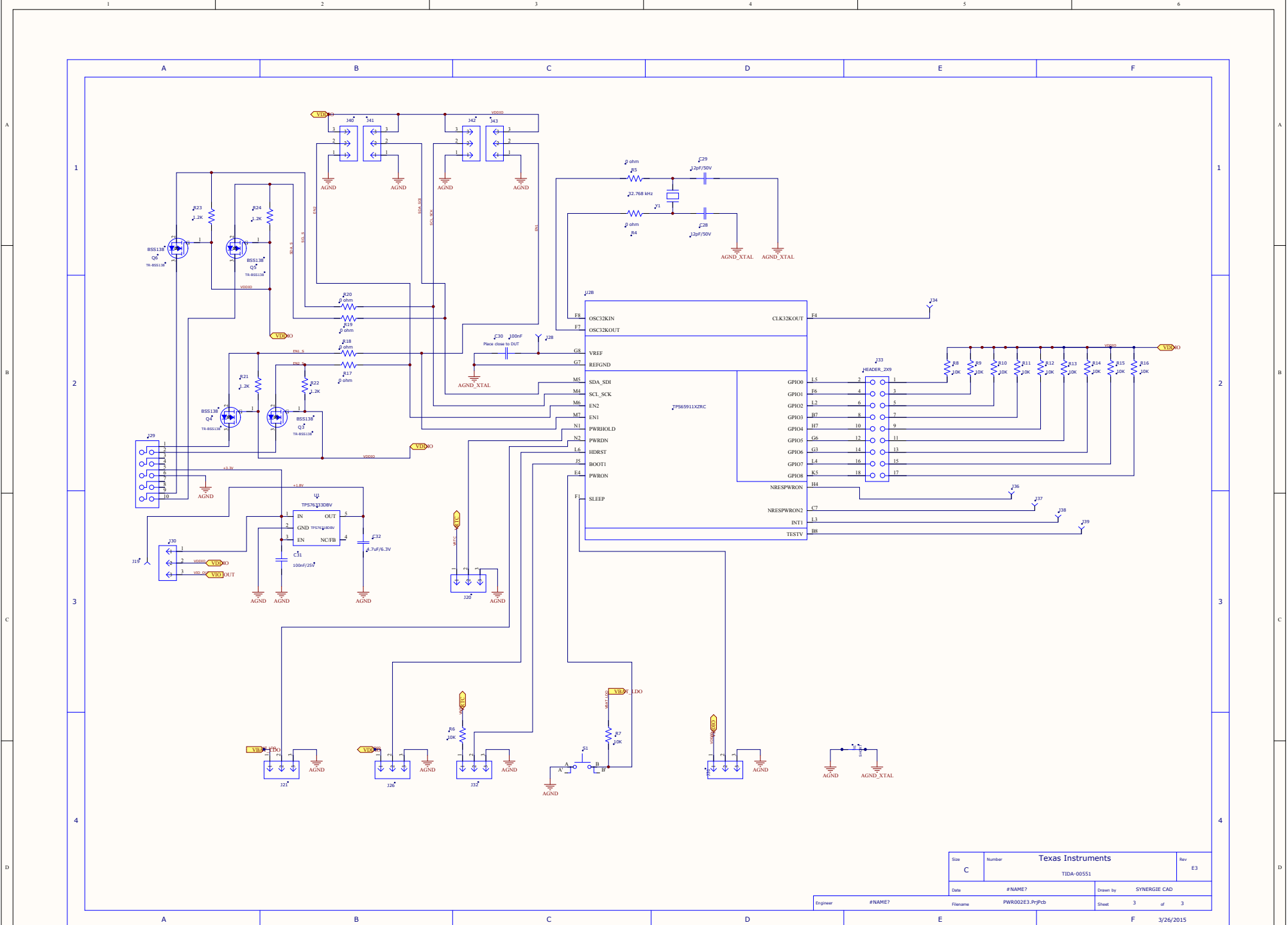


Xilinx 7015 Net Mapping

- IV0 = VCCINT, VCCBRAM, MGTAVCC
- VCCPINT_1V0 = VCCPINT
- IV8 = VCCAUX, VCCO_1.8V, VCCO_MIO0/1, VCCPAUX, VCCPLL, VCCADC
- IV5 = VCCO_DDR, VCCO_1.5V
- IV2 = VCCO_1.2V, MGTAVTT
- IV35 = VCCO_1.35V
- 2V5 = VCCO_2.5V
- 3V3 = VCCO_3.3V

Texas Instruments			
TIDA-00551			
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Engineer	#NAME?		

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